Fabrication of Microelectronic Devices III, PH 547
Spring quarter

1. Low k dielectrics for MLM.
2. CMP. Basics and applications (insulators and metals)
3. Photolithography.
   a. Basic optics
   b. optical systems
   c. resist technology
   d. Deep UV sources
   e. e-beam and x-ray sources

Mid-term

4. Wet processing
   a. etching
   b. wafer cleaning issues
5. Dry processing
   a. dc, ac, and HD plasmas
   b. plasma etching
   c. plasma induced damage
6. Device packaging
7. Yield and reliability
   Statistical process control

Silvaco project due at the end of the quarter